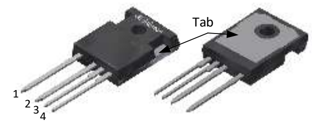
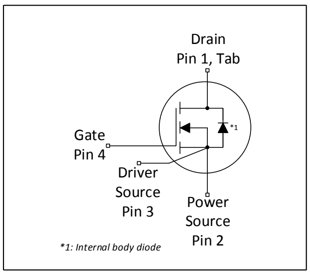
MOSFET

650 V CoolSiC™ M1 SiC Trench Power Device

The 650 V CoolSiC™ is built over the solid silicon carbide technology developed in Infineon in more than 20 years. Leveraging the wide bandgap SiC material characteristics, the 650V CoolSiC™ MOSFET offers a unique combination of performance, reliability and ease of use. Suitable for high temperature and harsh operations, it enables the simplified and cost effective deployment of the highest system efficiency.

PG-TO 247-4-3





Features

- Optimized switching behavior at higher currents
- Commutation robust fast body diode with low Q_{rr}
- Superior gate oxide reliability
- $T_{j,max}$=175°C and excellent thermal behavior
- Lower $R_{DS(on)}$ and pulse current dependency on temperature
- Increased avalanche capability
- Compatible with standard drivers (recommended driving voltage: 18V)
- Kelvin source provides up to 4 times lower switching losses

Benefits

- Unique combination of high performance, high reliability and ease of use
- Ease of use and integration
- Suitable for topologies with continuous hard commutation
- Higher robustness and system reliability
- Efficiency improvement
- Reduced system size leading to higher power density

Potential applications

- SMPS
- UPS (uninterruptable power supplies)
- Solar PV inverters
- EV charging infrastructure
- Energy storage and battery formation
- Class D amplifiers

Product validation

Fully qualified according to JEDEC for Industrial Applications

Please note: The source and driver source pins are not exchangeable. Their exchange might lead to malfunction.

Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS} @ T_J = 25 °C	650	V
$R_{DS(on),typ}$	83	mΩ
$R_{DS(on),max}$	111	mΩ
$Q_{G,typ}$	19	nC
$I_{D,pulse}$	59	A
Q_{oss} @ 400 V	44	nC
E_{oss} @ 400 V	6.6	µJ

Type / Ordering Code	Package	Marking	Related Links
IMZA65R083M1H	PG-TO247-4-3	65R083M1	see Appendix A

Table of Contents

1 Maximum ratings

at T_J = 25 °C, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current[1]	I_D	- -	- -	26 18	A	T_C = 25 °C T_C = 100 °C
Pulsed drain current[2]	$I_{D,pulse}$	-	-	59	A	T_C = 25 °C
Avalanche energy, single pulse	E_{AS}	-	-	95	mJ	I_D = 3.6 A, V_{DD} = 50 V, L = 14.7 mH; see table 10
Avalanche energy, repetitive	E_{AR}	-	-	0.48	mJ	I_D = 3.6 A, V_{DD} = 50 V; see table 10
Avalanche current, single pulse	I_{AS}	-	-	3.6	A	-
MOSFET *dv/dt* ruggedness	*dv/dt*	-	-	200	V/ns	V_{DS} = 0...400 V
Gate source voltage (static)	V_{GS}	-2	-	20	V	static
Gate source voltage (recommended driving voltage)	V_{GS}	0	-	18	V	-
Gate source voltage (dynamic)	V_{GS}	-5	-	23	V	$t_{pulse,negative}$ <= 15 ns $t_{pulse,positive}$ <= 1% duty cycle/f_{sw}
Power dissipation	P_{tot}	-	-	104	W	T_C = 25 °C
Storage temperature	T_{stg}	-55	-	150	°C	-
Operating junction temperature	T_J	-55	-	175	°C	-
Mounting torque	-	-	-	60	Ncm	M3 and M3.5 screws
Continuous diode forward current[1]	I_S	-	-	26	A	T_C = 25 °C
Diode pulse current[2]	$I_{S,pulse}$	-	-	59	A	T_C = 25 °C
Insulation withstand voltage	V_{ISO}	-	-	n.a.	V	V_{rms}, T_C = 25 °C, t = 1 min

[1] Limited by $T_{J,max}$
[2] Pulse width t_p limited by $T_{J,max}$

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	1.44	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	°C/W	leaded
Thermal resistance, junction - ambient for SMD version	R_{thJA}	-	-	-	°C/W	n.a.
Soldering temperature, wavesoldering only allowed at leads	T_{sold}	-	-	260	°C	1.6mm (0.063 in.) from case for 10s

3 Electrical characteristics

at T_J = 25 °C, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	650	-	-	V	V_{GS} = 0 V, I_D = 0.33 mA
Gate threshold voltage[1]	$V_{(GS)th}$	3.5	4.5	5.7	V	V_{DS} = V_{GS}, I_D = 3.3 mA
Zero gate voltage drain current	I_{DSS}	- -	1 3	150 -	µA	V_{DS} = 650 V, V_{GS} = 0 V, T_J = 25 °C V_{DS} = 650 V, V_{GS} = 0 V, T_J = 175 °C
Gate-source leakage current	I_{GSS}	-	-	100	nA	V_{GS} = 20 V, V_{DS} = 0 V
Drain-source on-state resistance	$R_{DS(on)}$	- -	0.083 0.116	0.111 -	Ω	V_{GS} = 18 V, I_D = 11.2 A, T_J = 25 °C V_{GS} = 18 V, I_D = 11.2 A, T_J =175 °C
Gate resistance	R_G	-	10.0	-	Ω	f = 1 MHz, open drain

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	624	-	pF	V_{GS} = 0 V, V_{DS} = 400 V, f = 250 kHz
Reverse capacitance	C_{rss}	-	8	-	pF	V_{GS} = 0 V, V_{DS} = 400 V, f = 250 kHz
Output capacitance[2]	C_{oss}	-	73	95	pF	V_{GS} = 0 V, V_{DS} = 400 V, f = 250 kHz
Output charge[2]	Q_{oss}	-	44	57	nC	calculation based on C_{oss}
Effective output capacitance, energy related[3]	$C_{o(er)}$	-	82	-	pF	V_{GS} = 0 V, V_{DS} = 0...400 V
Effective output capacitance, time related[4]	$C_{o(tr)}$	-	109	-	pF	I_D = constant, V_{GS} = 0 V, V_{DS} = 0...400 V
Turn-on delay time	$t_{d(on)}$	-	10.0	-	ns	V_{DD} = 400 V, V_{GS} = 18 V, I_D = 11.2 A, R_G = 1.8 Ω; see table 9
Rise time	t_r	-	7.0	-	ns	V_{DD} = 400 V, V_{GS} = 18 V, I_D = 11.2 A, R_G = 1.8 Ω; see table 9
Turn-off delay time	$t_{d(off)}$	-	14.0	-	ns	V_{DD} = 400 V, V_{GS} = 18 V, I_D = 11.2 A, R_G = 1.8 Ω; see table 9
Fall time	t_f	-	7.0	-	ns	V_{DD} = 400 V, V_{GS} = 18 V, I_D = 11.2 A, R_G = 1.8 Ω; see table 9

[1] Tested after 1 ms pulse at V_{GS} = +20 V
[2] Maximum specification is defined by calculated six sigma upper confidence bound
[3] $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 400 V
[4] $C_{o(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 400 V

Table 6 Gate charge characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	5	-	nC	V_{DD} = 400 V, I_D = 11.2 A, V_{GS} = 0 to 18 V
Gate to drain charge	Q_{gd}	-	4	-	nC	V_{DD} = 400 V, I_D = 11.2 A, V_{GS} = 0 to 18 V
Gate charge total	Q_g	-	19	-	nC	V_{DD} = 400 V, I_D = 11.2 A, V_{GS} = 0 to 18 V

Table 7 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	V_{SD}	-	4.0	-	V	V_{GS} = 0 V, I_F = 11.2 A, T_J = 25 °C
Reverse recovery time	t_{rr}	-	22	-	ns	V_R = 400 V, I_F = 11.2 A, di_F/dt = 1000 A/µs; see table 8
Reverse recovery charge	Q_{rr}	-	82	-	nC	V_R = 400 V, I_F = 11.2 A, di_F/dt = 1000 A/µs; see table 8
Peak reverse recovery current	I_{rrm}	-	7.5	-	A	V_R = 400 V, I_F = 11.2 A, di_F/dt = 1000 A/µs; see table 8

4 Electrical characteristics diagrams

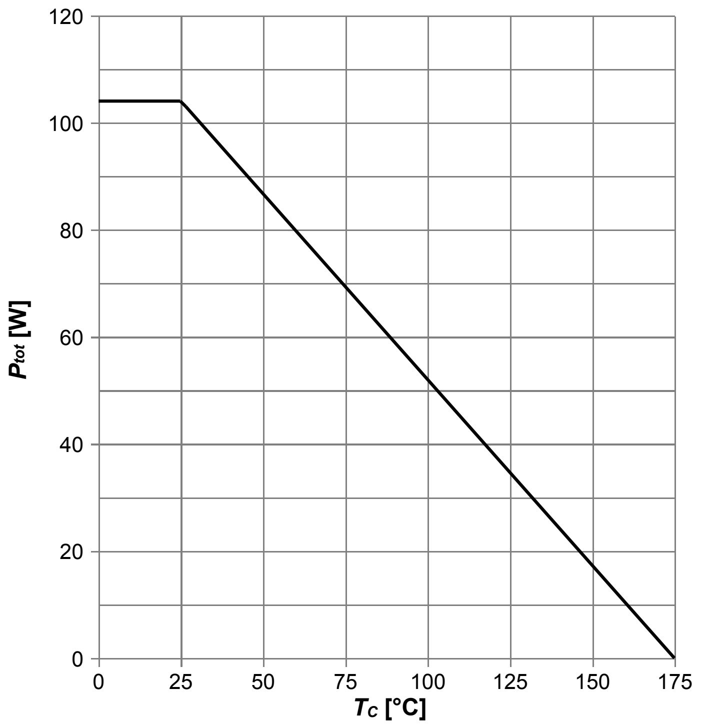
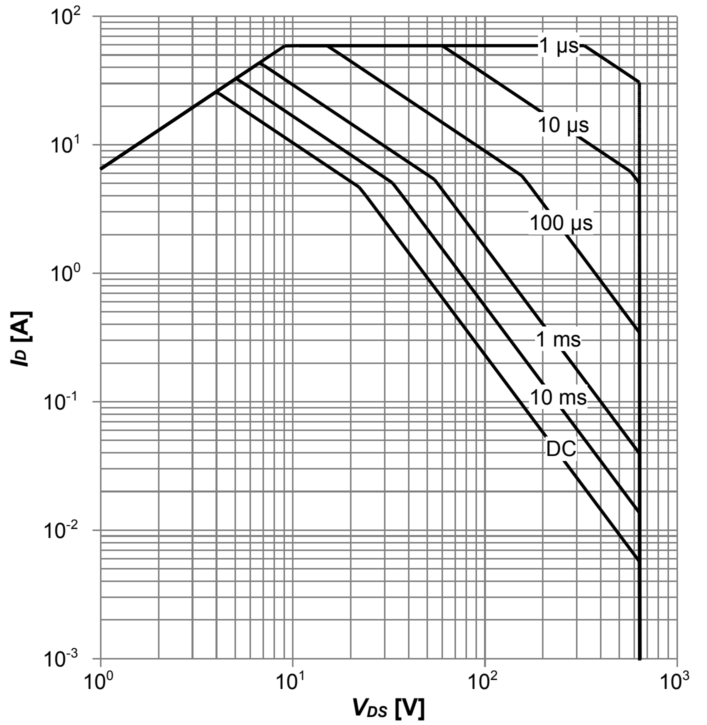
Diagram 1: Power dissipation	Diagram 2: Safe operating area
	
$P_{tot}=f(T_C)$	$I_D=f(V_{DS})$; T_C=25 °C; D=0; parameter: t_p

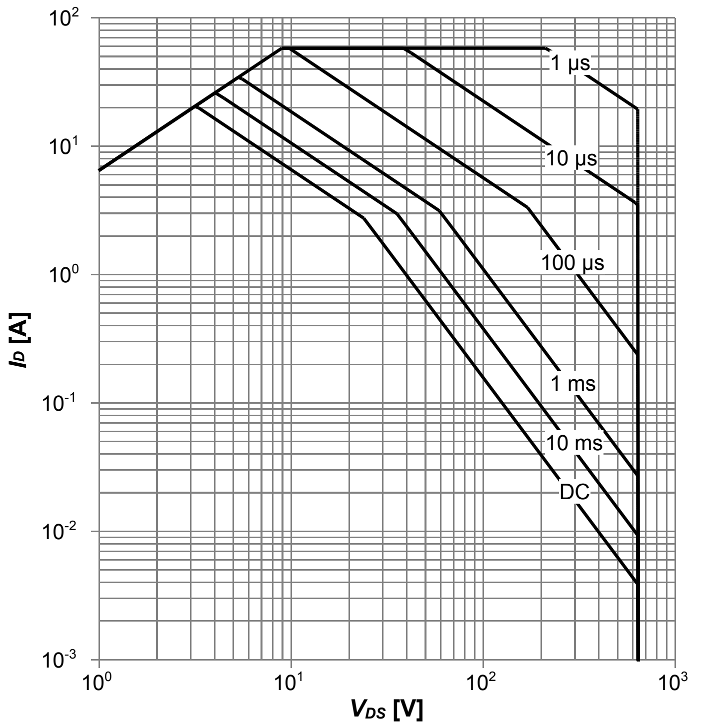
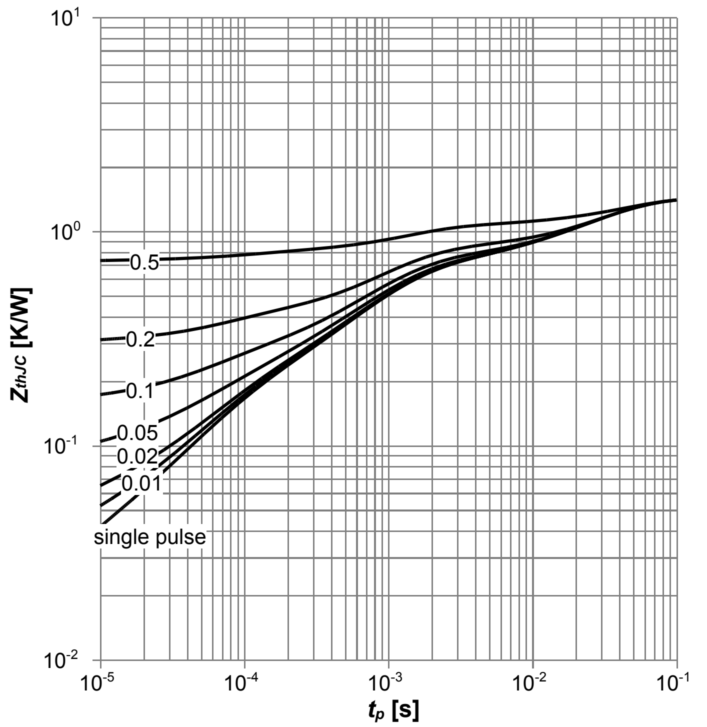
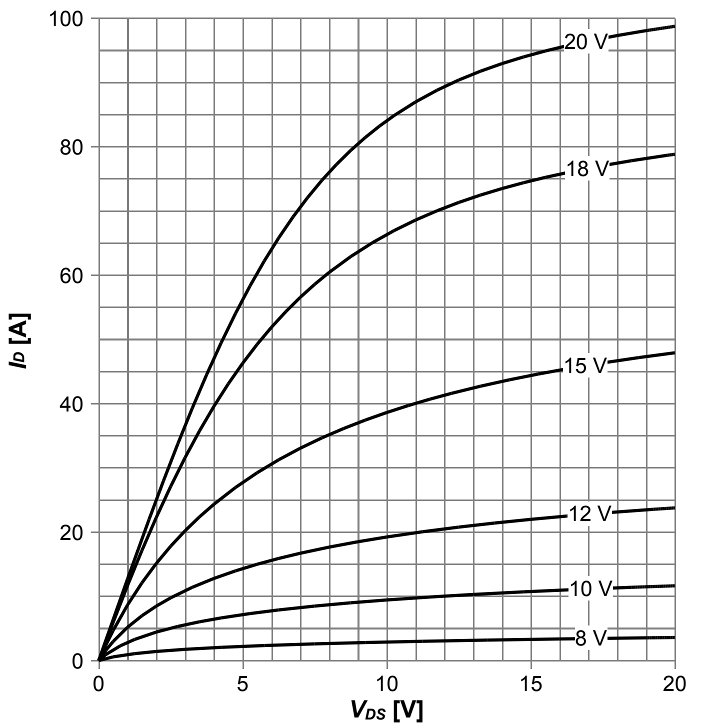
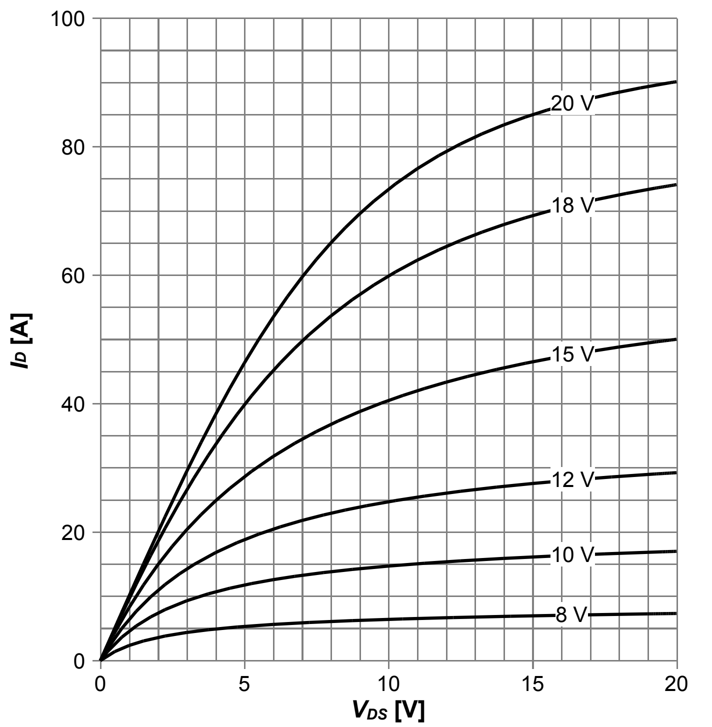
Diagram 3: Safe operating area	Diagram 4: Max. transient thermal impedance
	
$I_D=f(V_{DS})$; T_C=80 °C; D=0; parameter: t_p	$Z_{thJC}=f(t_P)$; parameter: $D=t_p/T$

Diagram 5: Typ. output characteristics



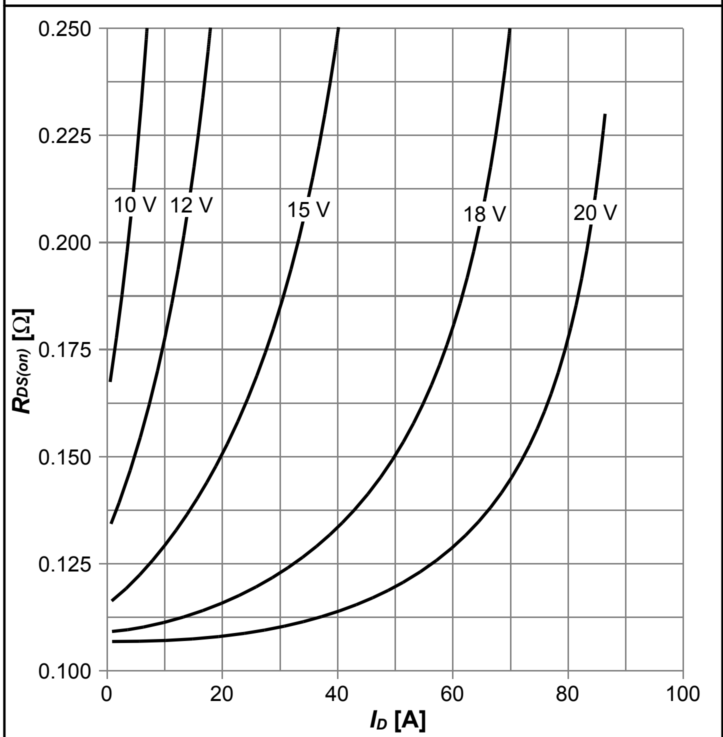
I_D=f(V_{DS}); T_j=25 °C; parameter: V_{GS}

Diagram 6: Typ. output characteristics



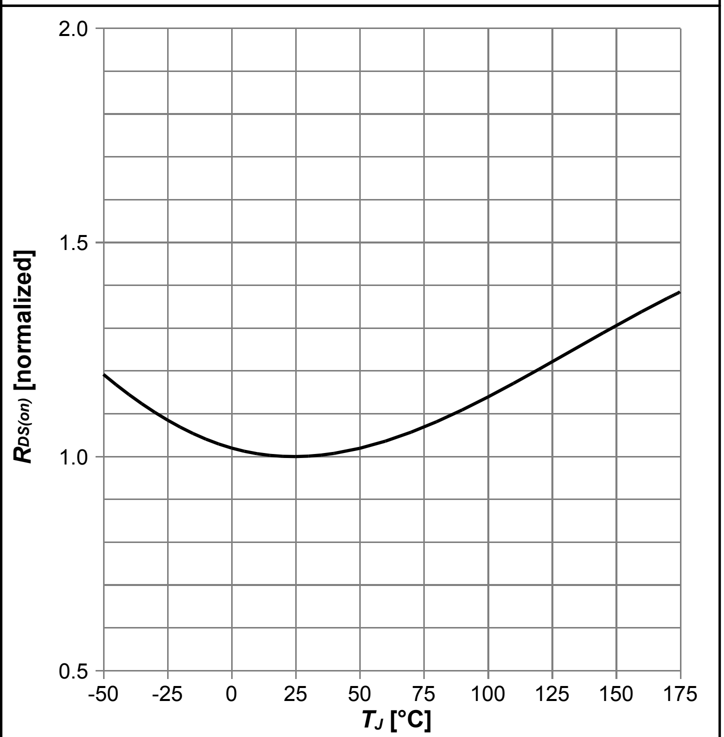
I_D=f(V_{DS}); T_j=125 °C; parameter: V_{GS}

Diagram 7: Typ. drain-source on-state resistance



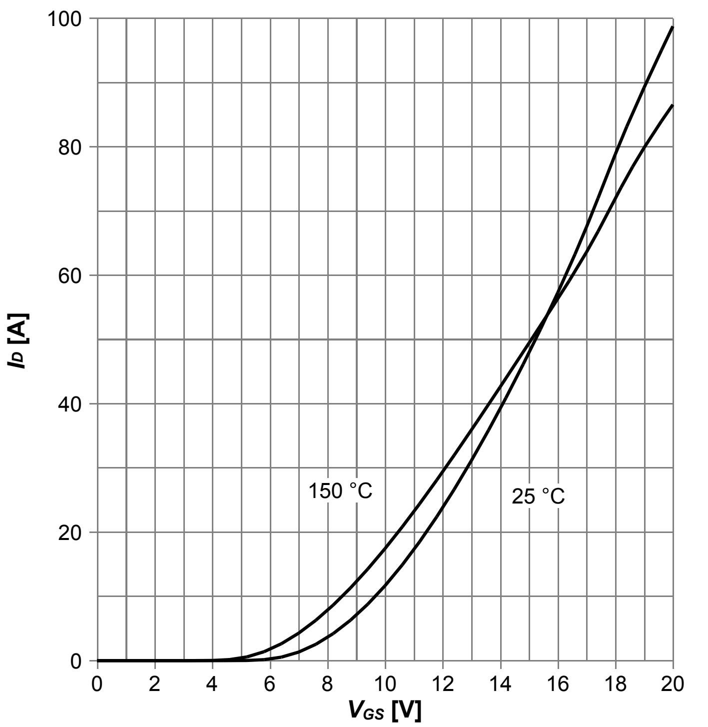
$R_{DS(on)}$=f(I_D); T_j=150 °C; parameter: V_{GS}

Diagram 8: Drain-source on-state resistance



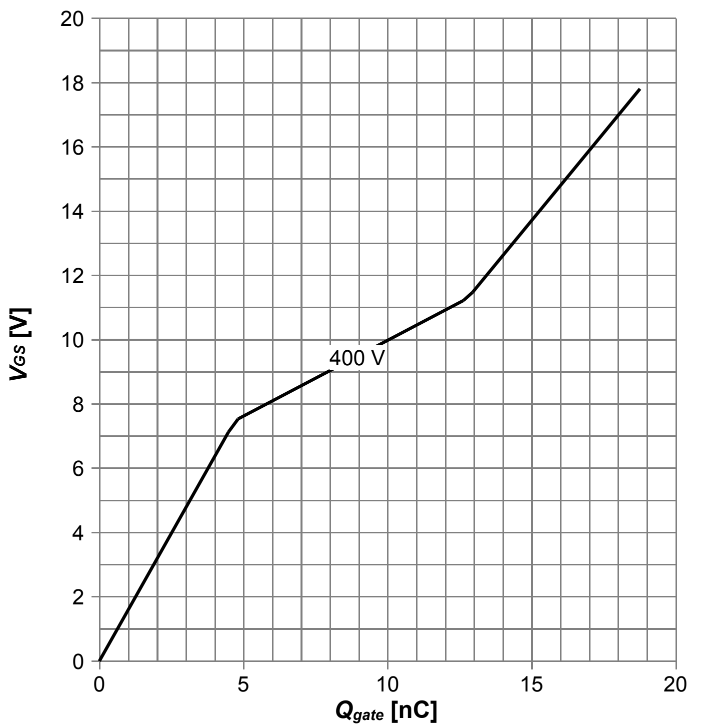
$R_{DS(on)}$=f(T_j); I_D=11.2 A; V_{GS}=18 V

Diagram 9: Typ. transfer characteristics



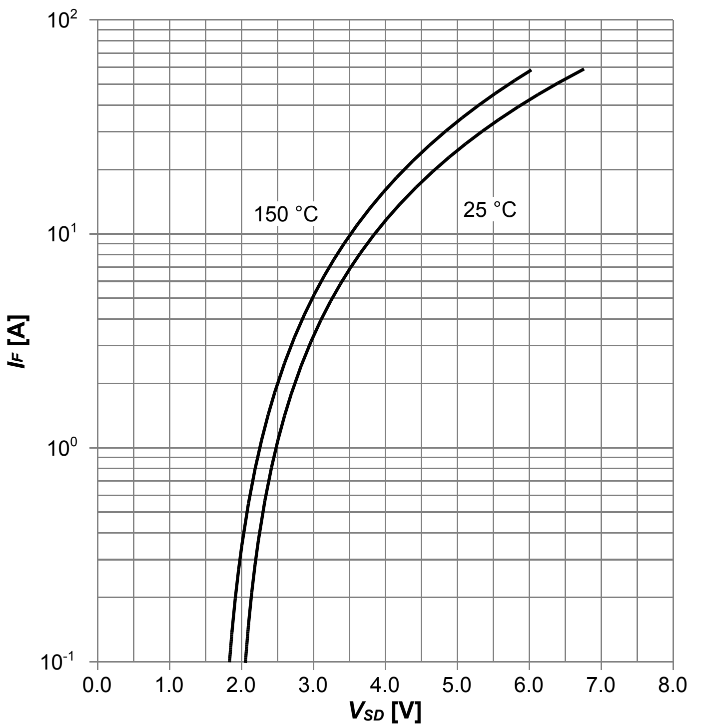
I_D=f(V_{GS}); V_{DS}=20V; parameter: T_j

Diagram 10: Typ. gate charge



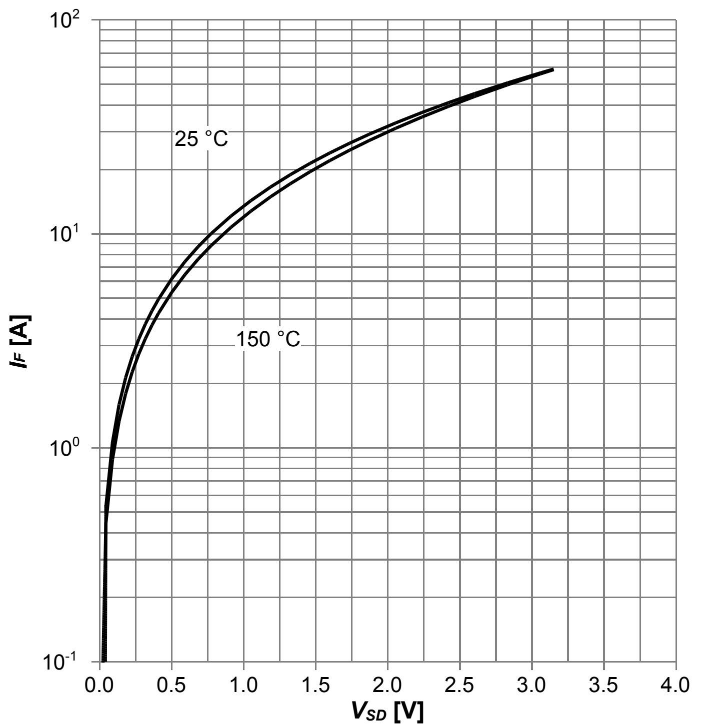
V_{GS}=f(Q_{gate}); I_D=11.2 A pulsed; parameter: V_{DD}

Diagram 11: Typ. forward characteristics of reverse diode



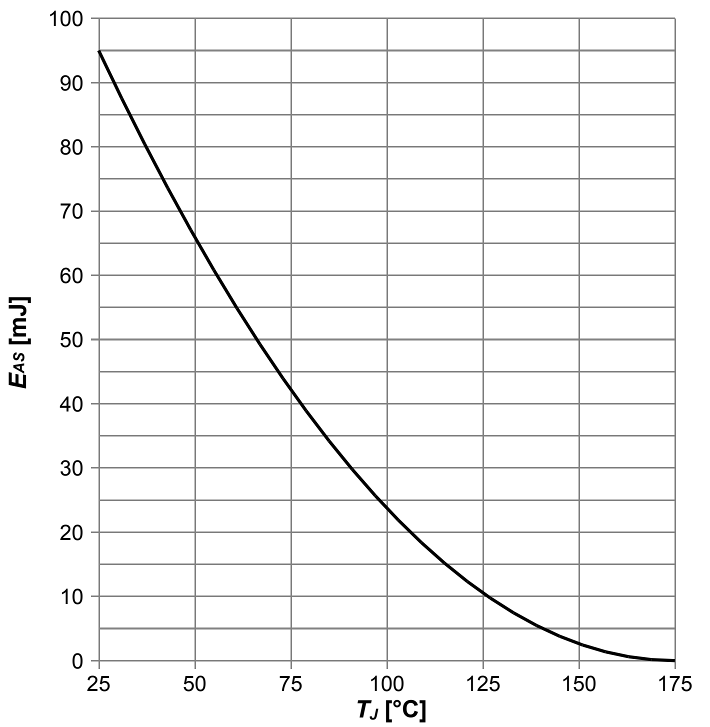
I_F=f(V_{SD}); parameter: T_j

Diagram 12: Typ. channel reverse characteristics



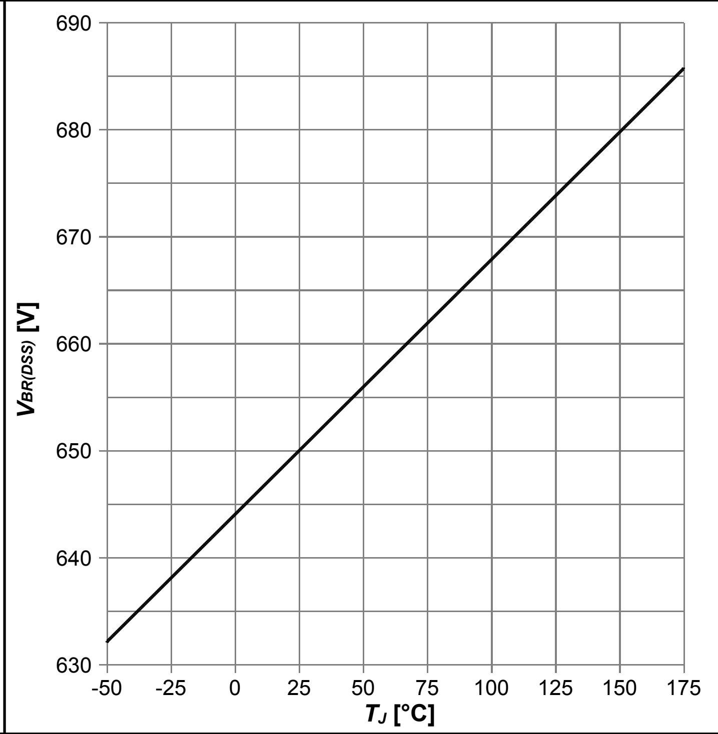
I_F=f(V_{SD}); V_{GS}=18 V; parameter: T_j

Diagram 13: Avalanche energy



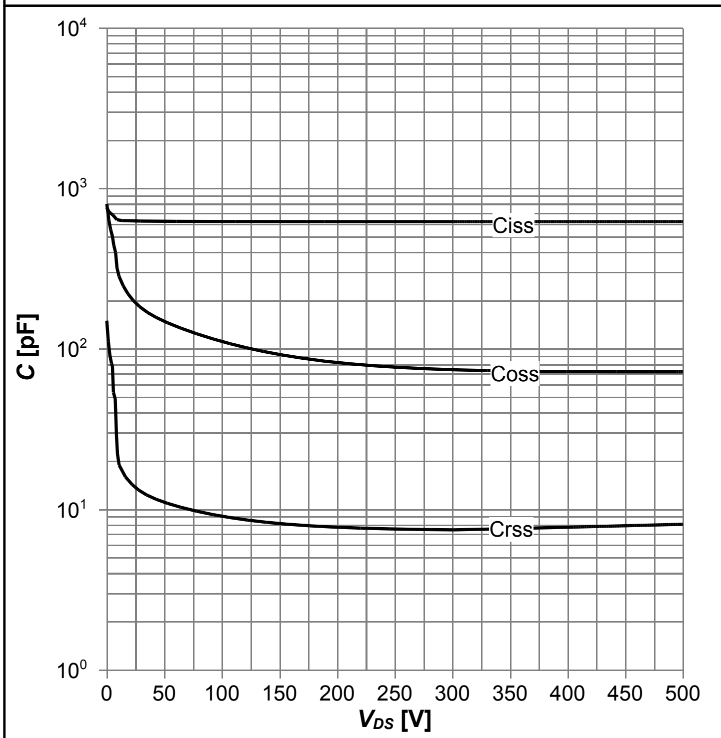
E_{AS}=f(T_j); I_D=3.6 A; V_{DD}=50 V

Diagram 14: Drain-source breakdown voltage



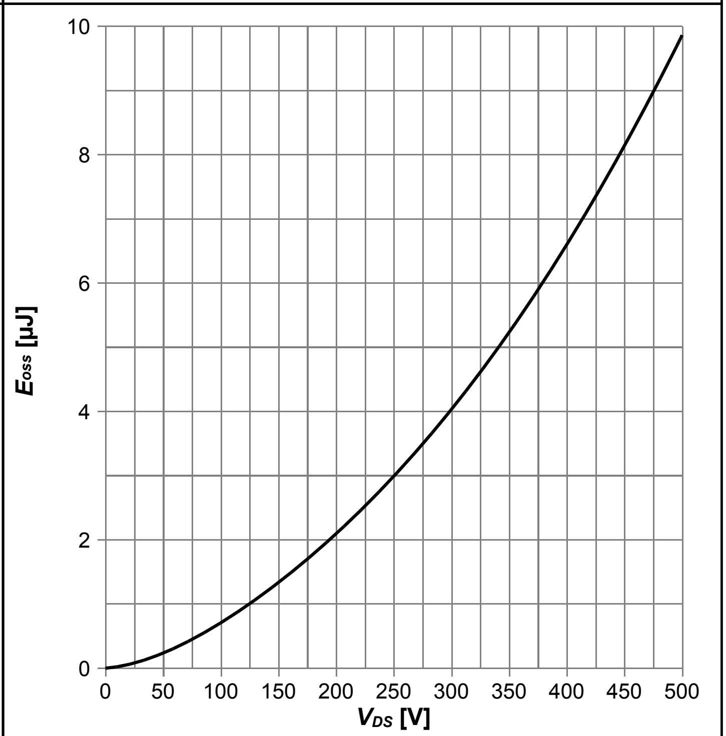
$V_{BR(DSS)}$=f(T_j); I_D=0.33 mA

Diagram 15: Typ. capacitances



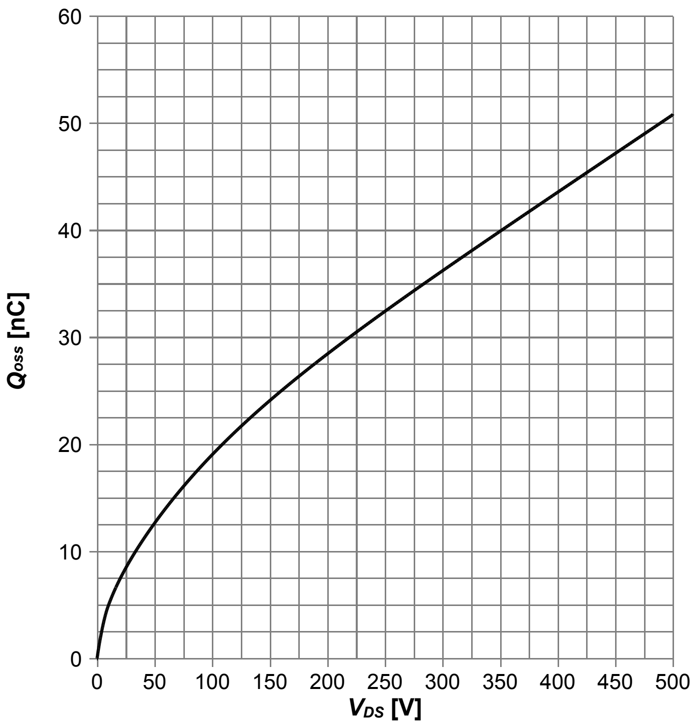
C=f(V_{DS}); V_{GS}=0 V; f=250 kHz

Diagram 16: Typ. Coss stored energy



E_{oss}=f(V_{DS})

Diagram 17: Typ. Qoss output charge



Q_{oss}=f(V_{DS})

5 Test Circuits

Table 8 Diode characteristics (ss) (SiC)

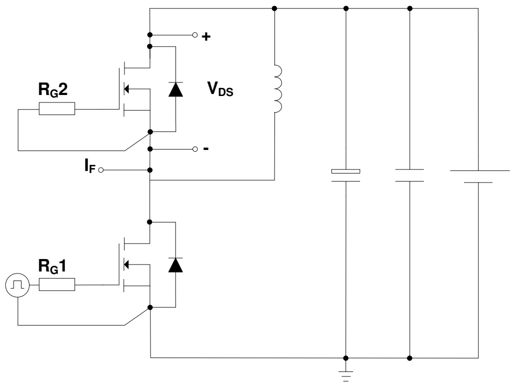
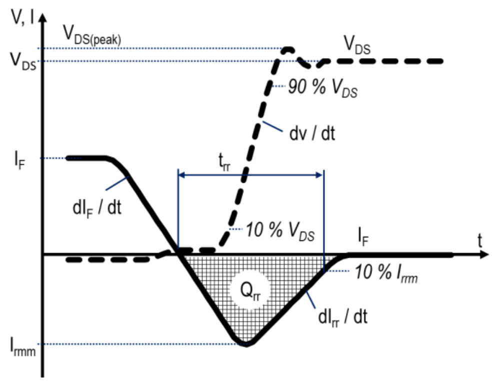
Test circuit for diode characteristics	Diode recovery waveform
	

Table 9 Switching times (ss) (SiC)

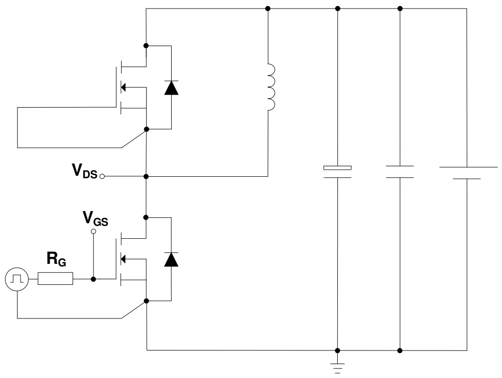
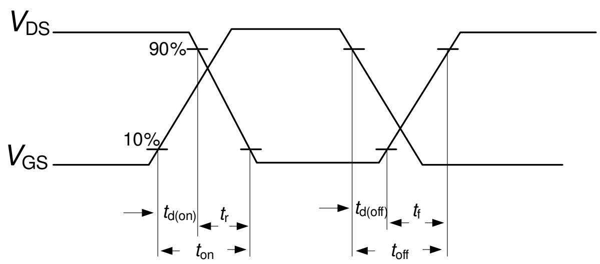
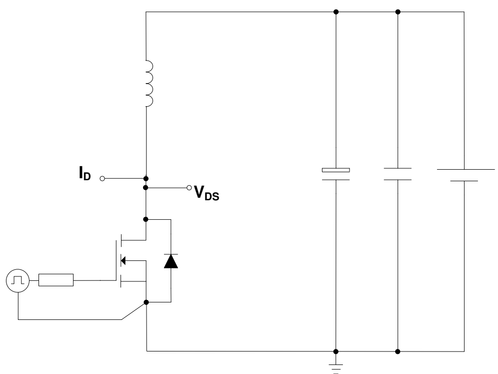
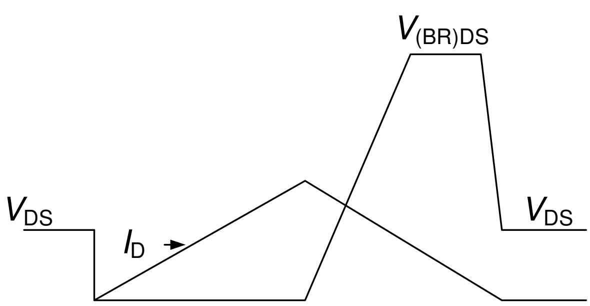
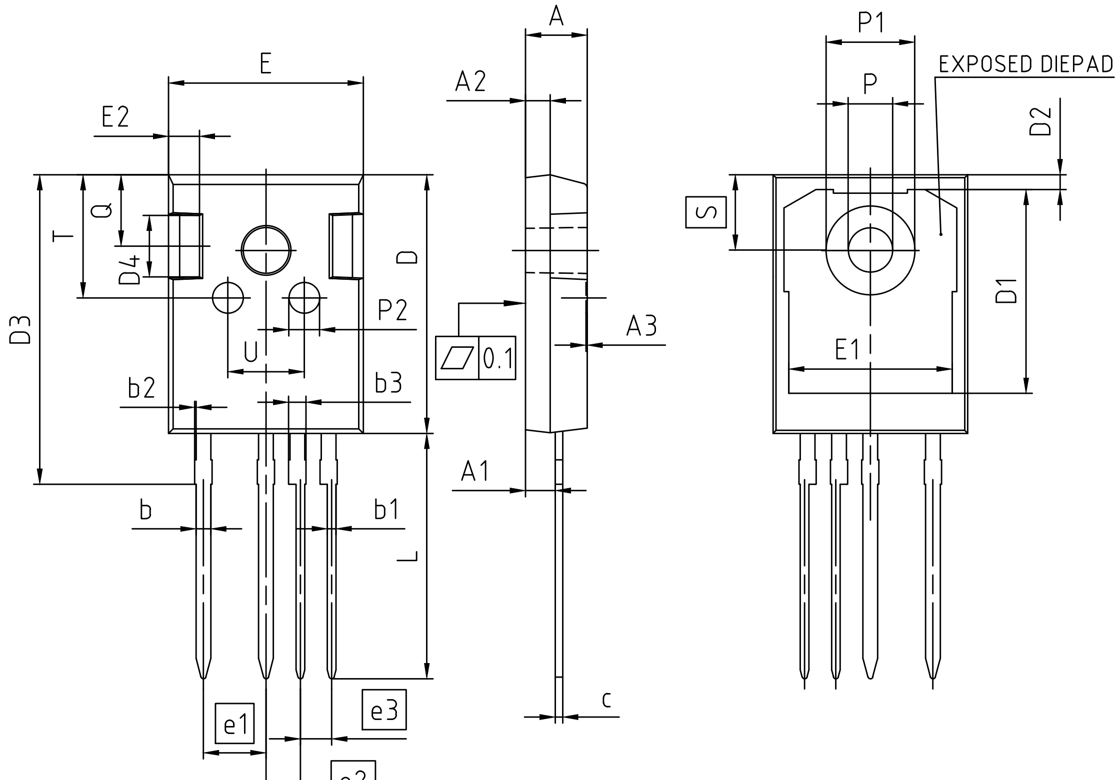
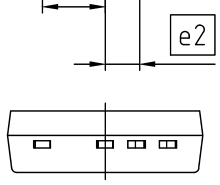
Switching times test circuit for inductive load	Switching times waveform
	

Table 10 Unclamped inductive load (ss) (SiC)

Unclamped inductive load test circuit	Unclamped inductive waveform
	

6 Package Outlines





NOTES:
ALL DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	4.90	5.10
A1	2.31	2.51
A2	1.90	2.10
A3	0.05	0.25
b	1.10	1.30
b1	0.65	0.79
b2	-	0.20
b3	1.34	1.44
c	0.58	0.66
D	20.90	21.10
D1	16.25	16.85
D2	1.05	1.35
D3	24.97	25.27
D4	4.90	5.10
E	15.70	15.90
E1	13.10	13.50
E2	2.40	2.60
e1	5.08	
e2	2.79	
e3	2.54	
L	19.80	20.10
L1	-	4.30
øP	3.50	3.70
øP1	7.00	7.40
øP2	2.40	2.60
Q	5.60	6.00
S	6.15	
T	9.80	10.20
U	6.00	6.40

DOCUMENT NO.
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REVISION
03

SCALE 2:1
0 5 10mm

EUROPEAN PROJECTION

ISSUE DATE
21.08.2017

Figure 1 Outline PG-TO247-4-3, dimensions in mm

7 Appendix A

Table 11 Related Links

- **IFX CoolSiC M1 Webpage:** www.infineon.com
- **IFX CoolSiC M1 application note:** www.infineon.com
- **IFX CoolSiC M1 simulation model:** www.infineon.com
- **IFX Design tools:** www.infineon.com

Revision History

IMZA65R083M1H

Revision: 2021-03-17, Rev. 2.0

Previous Revision		
Revision	Date	Subjects (major changes since last revision)
2.0	2021-03-17	Release of final version

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